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Advanced Properties of Engineering Thin Films and Materials

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Deadline for manuscript
submissions:

closed (20 March 2023)

Message from the Guest Editor

Engineering thin films and materials refer to the materials used in a variety of applications to withstand applied stress without failure. Engineering thin films and materials are mainly divided into metals, ceramics, polymers, and composites. This Special Issue covers the experimental and theoretical properties of engineering thin films and materials, as well as methods of synthesizing and analyzing engineering thin films and materials. Advanced properties of engineering thin films and materials include but are not limited to structural, elastic, mechanical, physical, chemical, thermal, thermodynamic, electrical, and optical properties.

All manuscripts containing properties and methods of materials for engineering applications are welcome in this Special Issue. Based on the information above, this Special Issue invites manuscripts on all types of engineering thin films and materials.



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Special Issue



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Message from the Editor-in-Chief

Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

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